

### Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### Features

- ◆ 40V, 100A,  $R_{DS(ON).max}=5.0m\Omega@V_{GS}=10V$
- ◆ Improved dv/dt capability
- ◆ Fast switching
- ◆ 100% EAS Guaranteed
- ◆ Green device available

### Applications

- ◆ Motor Drives
- ◆ UPS
- ◆ DC-DC Converter

### Product Summary

|                             |               |
|-----------------------------|---------------|
| $V_{DSS}$                   | 40V           |
| $R_{DS(on).max}@V_{GS}=10V$ | 5.0m $\Omega$ |
| $I_D$                       | 100A          |

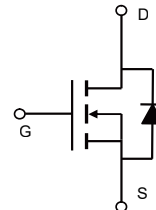
### Pin Configuration



TO-252



TO-251



Schematic

### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

| Parameter  | Symbol    | Value       | Unit             |
|--|-----------|-------------|------------------|
| Drain-Source Voltage                                   | $V_{DSS}$ | 40          | V                |
| Continuous drain current ( $T_C = 25^\circ\text{C}$ )  | $I_D$     | 100         | A                |
| Continuous drain current ( $T_C = 100^\circ\text{C}$ ) |           | 70          | A                |
| Pulsed drain current <sup>1)</sup>                     | $I_{DM}$  | 400         | A                |
| Gate-Source voltage                                    | $V_{GSS}$ | $\pm 20$    | V                |
| Avalanche energy <sup>2)</sup>                         | $E_{AS}$  | 156         | mJ               |
| Power Dissipation ( $T_C = 25^\circ\text{C}$ )         | $P_D$     | 100         | W                |
| Storage Temperature Range                              | $T_{STG}$ | -55 to +150 | $^\circ\text{C}$ |
| Operating Junction Temperature Range                   | $T_J$     | -55 to +150 | $^\circ\text{C}$ |

### Thermal Characteristics

| Parameter                            | Symbol          | Value | Unit               |
|--------------------------------------|-----------------|-------|--------------------|
| Thermal Resistance, Junction-to-Case | $R_{\theta JC}$ | 1.25  | $^\circ\text{C/W}$ |

## Package Marking and Ordering Information

| Device       | Device Package | Marking      |
|--------------|----------------|--------------|
| VSM100N04-T2 | TO-252         | VSM100N04-T2 |
| VSM100N04-T1 | TO-251         | VSM100N04-T1 |

## Electrical Characteristics

 $T_J = 25^{\circ}\text{C}$  unless otherwise noted

| Parameter  | Symbol              | Test Condition  | Min. | Typ.   | Max. | Unit |
|--|---------------------|---|------|--------|------|------|
| Static characteristics                                 |                     |   |      |        |      |      |
| Drain-source breakdown voltage                         | BV <sub>DSS</sub>   | V <sub>GS</sub> =0 V, I <sub>D</sub> =250uA                         | 40   | ---    | ---  | V    |
| Gate threshold voltage                                 | V <sub>GS(th)</sub> | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA            | 1.0  | ---    | 2.0  | V    |
| Drain-source leakage current                           | I <sub>DSS</sub>    | V <sub>DS</sub> =40 V, V <sub>GS</sub> =0 V, T <sub>J</sub> = 25°C  | ---  | ---    | 1    | μA   |
|  |                     | V <sub>DS</sub> =32 V, V <sub>GS</sub> =0 V, T <sub>J</sub> = 125°C | ---  | ---    | 30   | μA   |
| Gate leakage current, Forward                          | I <sub>GSSF</sub>   | V <sub>GS</sub> =20 V, V <sub>DS</sub> =0 V                         | ---  | ---    | 100  | nA   |
| Gate leakage current, Reverse                          | I <sub>GSSR</sub>   | V <sub>GS</sub> =-20 V, V <sub>DS</sub> =0 V                        | ---  | ---    | -100 | nA   |
| Drain-source on-state resistance                       | R <sub>DS(on)</sub> | V <sub>GS</sub> =10 V, I <sub>D</sub> =40 A                         | ---  | 3.8    | 5    | mΩ   |
|  |                     | V <sub>GS</sub> =4.5 V, I <sub>D</sub> =30 A                        | ---  | 4.7    | 6.2  | mΩ   |
| Forward transconductance                               | g <sub>fs</sub>     | V <sub>DS</sub> =5 V , I <sub>D</sub> =30 A                         | ---  | 79     | ---  | S    |
| Dynamic characteristics                                |                     |   |      |        |      |      |
| Input capacitance                                      | C <sub>iss</sub>    | V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V,<br>F = 1MHz          | ---  | 4023.6 | ---  | pF   |
| Output capacitance                                     | C <sub>oss</sub>    |   | ---  | 410.4  | ---  |      |
| Reverse transfer capacitance                           | C <sub>rss</sub>    |   | ---  | 338.5  | ---  |      |
| Turn-on delay time                                     | t <sub>d(on)</sub>  | V <sub>DD</sub> = 30V,V <sub>GS</sub> =15V, I <sub>D</sub> =30 A    | ---  | 231.6  | ---  | ns   |
| Rise time  | t <sub>r</sub>      |   | ---  | 213.6  | ---  |      |
| Turn-off delay time                                    | t <sub>d(off)</sub> |   | ---  | 219.2  | ---  |      |
| Fall time  | t <sub>f</sub>      |   | ---  | 74     | ---  |      |
| Gate resistance  | R <sub>g</sub>      | V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz                    | ---  | 2.4    | ---  | Ω    |
| Gate charge characteristics                            |                     |   |      |        |      |      |
| Gate to source charge                                  | Q <sub>gs</sub>     | V <sub>DS</sub> =30 V, I <sub>D</sub> =30A,<br>V <sub>GS</sub> =10V | ---  | 11     | ---  | nC   |
| Gate to drain charge                                   | Q <sub>gd</sub>     |   | ---  | 16.7   | ---  |      |
| Gate charge total                                      | Q <sub>g</sub>      |   | ---  | 66.7   | ---  |      |
| Drain-Source diode characteristics and Maximum Ratings |                     |   |      |        |      |      |
| Continuous Source Current                              | I <sub>S</sub>      |   | ---  | ---    | 100  | A    |
| Pulsed Source Current <sup>3)</sup>                    | I <sub>SM</sub>     |   | ---  | ---    | 400  | A    |
| Diode Forward Voltage                                  | V <sub>SD</sub>     | V <sub>GS</sub> =0V, I <sub>S</sub> =40A, T <sub>J</sub> =25°C      | ---  | ---    | 1.2  | V    |
| Reverse Recovery Time                                  | t <sub>rr</sub>     | I <sub>S</sub> =20A,di/dt=100A/us, T <sub>J</sub> =25°C             | ---  | 41.4   | ---  | ns   |
| Reverse Recovery Charge                                | Q <sub>rr</sub>     |   | ---  | 29     | ---  | nC   |

Notes:

1: Repetitive Rating: Pulse width limited by maximum junction temperature.

2:  $V_{DD}=20\text{ V}, V_{GS}=10\text{ V}, L=0.5\text{ mH}, I_{AS}=25\text{ A}, R_G=25\Omega$ , Starting  $T_J=25^{\circ}\text{C}$ .

3: Pulse Test: Pulse Width  $\leq 300\mu\text{ s}$ , Duty Cycle  $\leq 2\%$ .

## Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

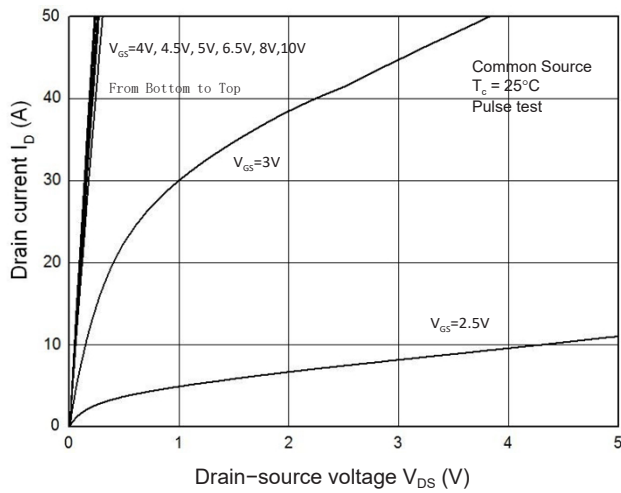


Figure 2. Transfer Characteristics

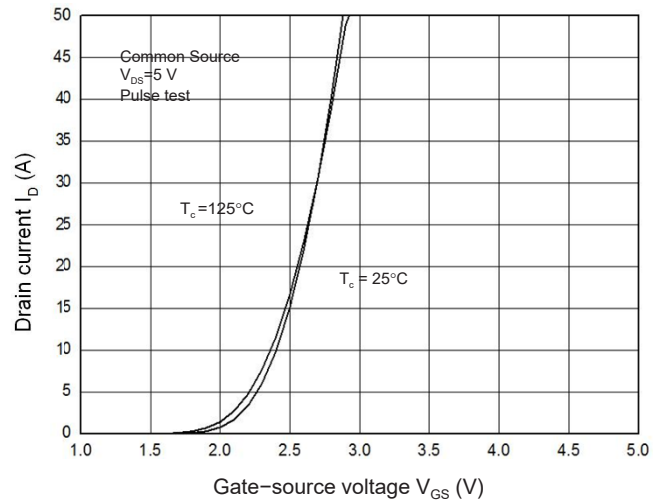


Figure 3. Capacitance Characteristics

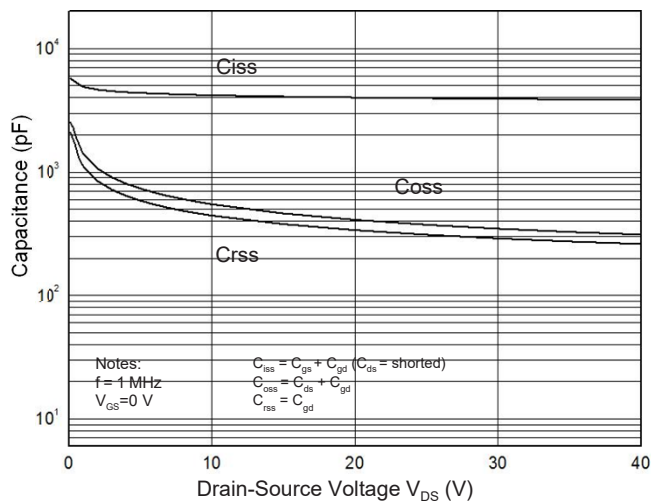


Figure 4. Gate Charge Waveform

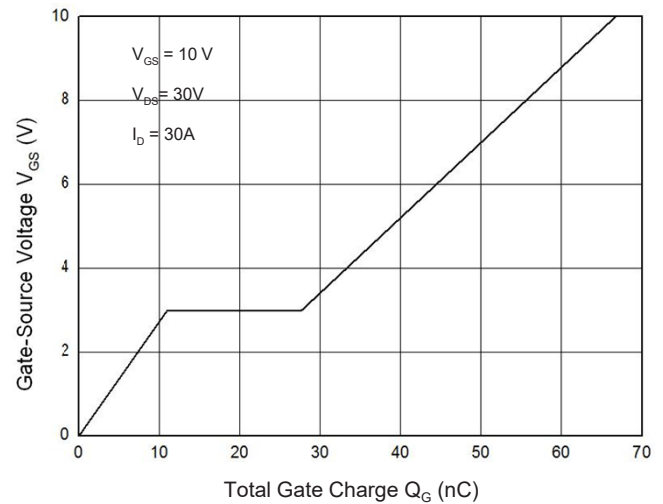


Figure 5. Body-Diode Characteristics

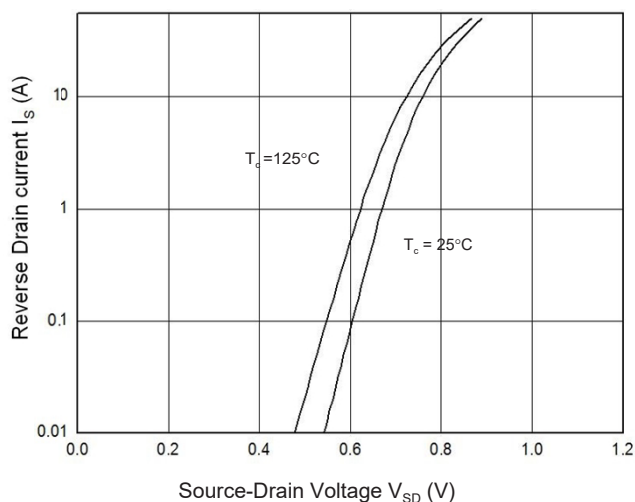


Figure 6. R\_DS(on)-Drain Current

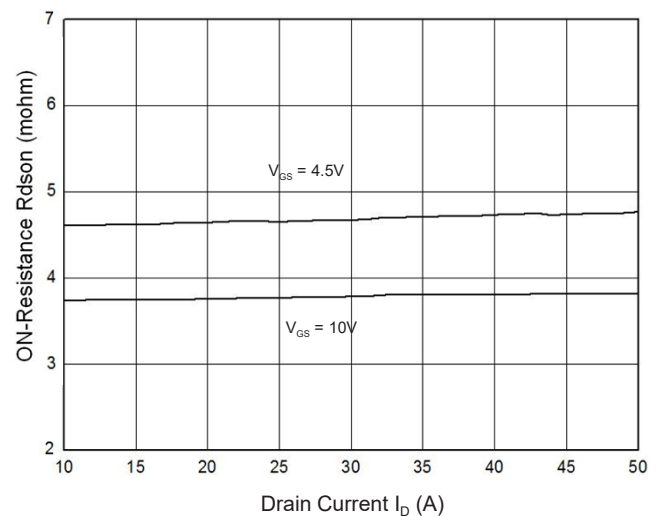


Figure 7. Rdson-Junction Temperature(°C)

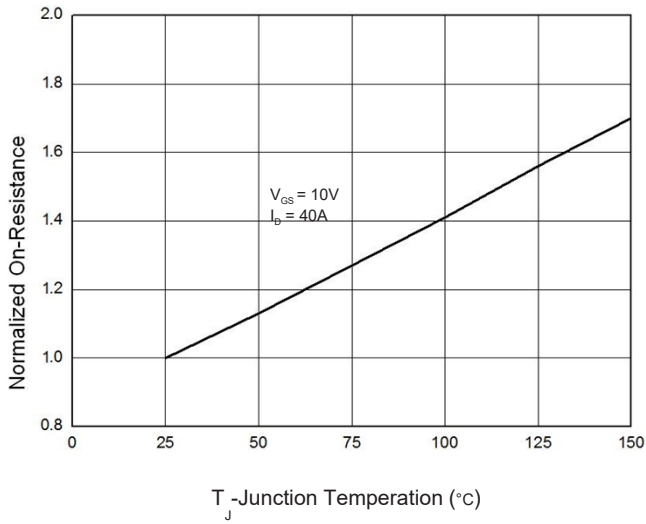


Figure 8. Maximum Safe Operating Area

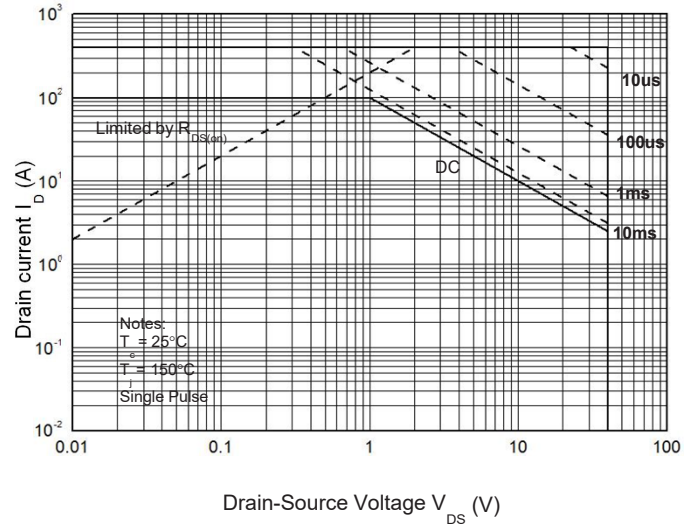
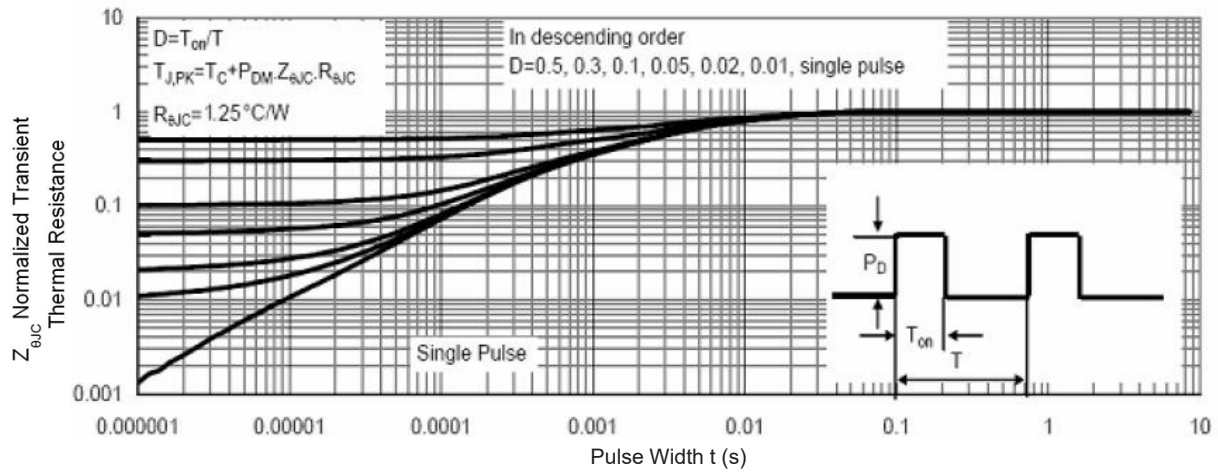


Figure 9. Normalized Maximum Transient Thermal Impedance (RthJC)



## Test Circuit & Waveform

Figure 8. Gate Charge Test Circuit & Waveform

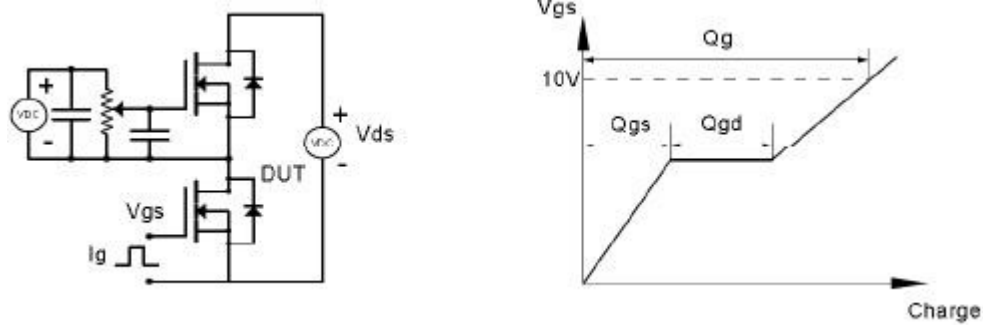


Figure 9. Resistive Switching Test Circuit & Waveforms

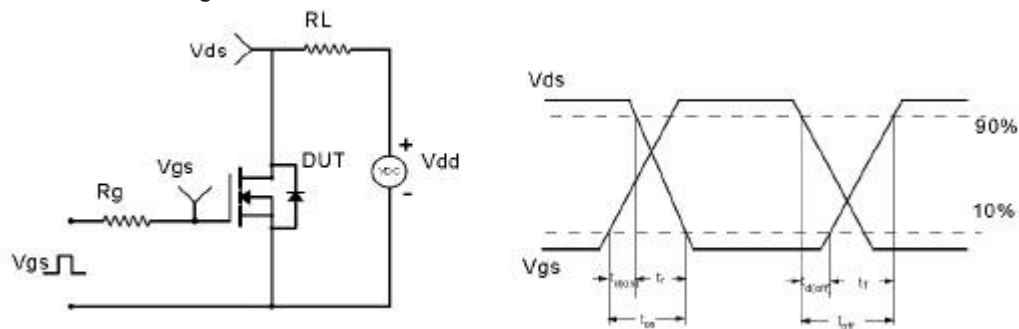


Figure 10. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

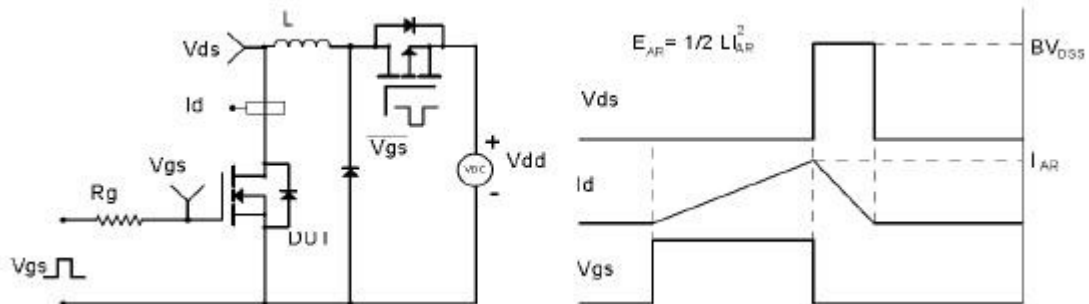


Figure 11. Diode Recovery Circuit & Waveform

